

SECTION II—CLAIMS

- 1.-13. (Canceled)
14. (Original) A process of forming a micro electromechanical (MEMS) package comprising:
- providing a semiconductor device;
 - providing a conveyance with at least one embedded MEMS device disposed therein; and
 - disposing the conveyance over the semiconductor device, wherein the at least one embedded MEMS device communicates electrically to the semiconductor device.
15. (Original) The process according to claim 14, wherein the at least one embedded MEMS device is selected from a switch, a capacitor, an inductor, an oscillator, a power supply, and combinations thereof.
16. (Original) The process according to claim 14, wherein the conveyance comprises a via disposed therein, the process further comprising:
- providing at least one detached MEMS device in a first structure; and
 - accommodating the at least one detached MEMS device through the via, upon the active surface.
17. (Original) The process according to claim 14, wherein the conveyance comprises a via disposed therein, the process further comprising:
- providing at least one detached MEMS device in a first structure;
 - placing the at least one detached MEMS device on the semiconductor device; and
 - accommodating the at least one detached MEMS device through the via, upon the active surface.
18. (Original) The process according to claim 14, wherein the conveyance comprises a via disposed therein, the process further comprising:
- providing at least one detached MEMS device in a first structure;
 - accommodating the at least one detached MEMS device upon the active surface;

providing a sealing structure; and

disposing the sealing structure in a manner sufficient to isolate at least one of the at least one detached MEMS device.

19. (Original) The process according to claim 14 further comprising:

forming an integrated package comprising the semiconductor device and the conveyance.

20. (Original) The process according to claim 14 further comprising:

forming an integrated package comprising the semiconductor device, the conveyance, and at least one detached MEMS device in a first structure, wherein the at least one detached MEMS device is accommodated upon the semiconductor device.

21. (Original) The process according to claim 20 further comprising:

encapsulating the detached MEMS device and the conveyance to form an integrated package.

22. (Original) The process according to claim 14 further comprising:

encapsulating the semiconductor device to form an integrated package, wherein the at least one detached MEMS device is accommodated upon the semiconductor device.

23. (Original) A process comprising:

providing a semiconductor device;

accommodating a detached micro electromechanical structure (MEMS) device upon the semiconductor device;

providing a conveyance over the semiconductor device and around the detached MEMS device; and

contacting encapsulation material with at least one of the semiconductor device, the detached MEMS device, and the conveyance to form an integrated MEMS package.

24. (Original) The process according to claim 23, further comprising:

embedding a MEMS device in the conveyance.

25. (Original) The process according to claim 23, further comprising:

providing a sealing structure; and

interposing the sealing structure upon the semiconductor device in a manner sufficient to isolate at least one of the at least one detached MEMS device.

26-30. (Canceled)